

Reliability-aware Data Placement for Heterogeneous memory Architecture

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Have you read everything on your car insurance?

ART. C.3 - ESCLUSIONI icurato ha diritto all'indennizzo validità permanente a zione che la stessa si manifesti due anni dall'Infortunio.

Sono esclusi dall'assicurazione i sinistri determinati da:

valutazione ssiva. Se la lesione comporta minorazione anziché la perdita anatomica o funzionale di o arti, le percentuali della vengono ridotte in alla orzione funzionalità ıta.

totale anatomica o perdita di più organi odarti onale l'applicazione di una orta di invaliditàpari alla ntuale delle singole percentuali osciute perciascuna lesione con ssimo del 100%. Per i casi non

dell'invalidità a) partecipazione a corse o gare e inente sarà effettuata in base alla relative prove ufficiali e verifiche che segue nella pagina preliminari e finali previste nel regolamento particolare di gara;

> b) tumulti popolari, atti di terrorismo, vandalismo, attentati ai quali l'Assicurato abbia partecipato attivamente;

c) guerra, insurrezioni, terremoti, eruzioni vulcaniche:

prede (b trasmutazione del nucleo anticir dell'atomo come pure dovuti ad sanita esposizione a radiazioni ionizzanti; preser incari

ART. C.4 - LIOUIDAZIONE

del piedeun arto inferiore all'altezza di sotto al ginocchio occhio ambedue gli occhi un rene milza sordità completa di un orecchi sordità completa di ambedue orecchi perdita totale del voce postumi di trauma distorsiv cervicale con contrattura muscolare limitazione dei movimenti del capo del collo

Liquidazione incaricato

Società

giustif

oppur

interv

Sanita

quota

danno

The insurance does not cover those accidents caused by:

[...]

exposure to ionizing radiation*

Reliability Matters





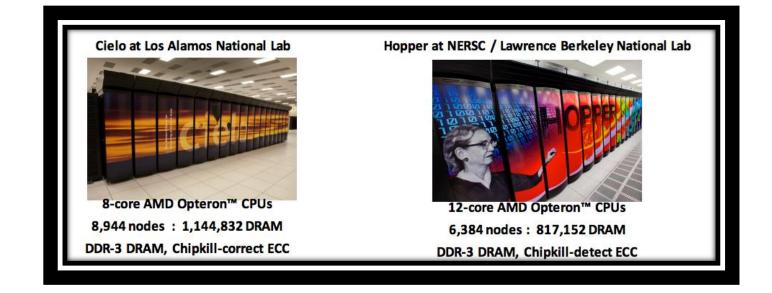
Autonomous vehicles

- Safety is important

High performance computing

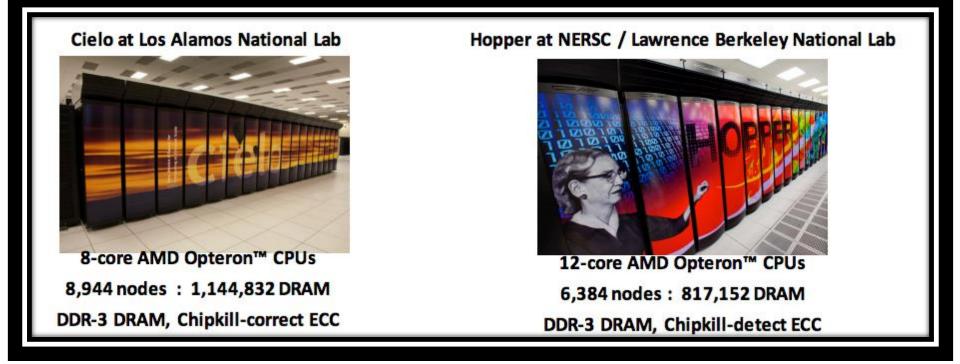
- Long running scientific jobs

Why Focus on Memory?



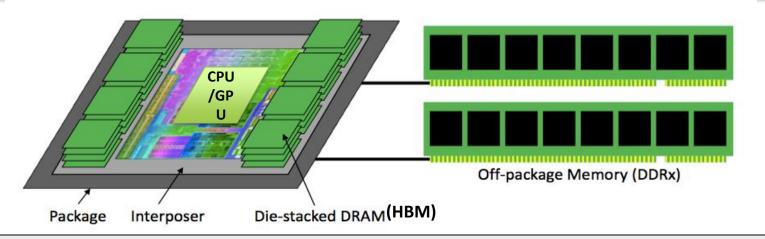
- Most of your computer is in fact memory
- The probability of a bit upset is proportional to silicon surface area

Large-scale Systems Magnifies Failures



Even though failure rate for each device seems low, the systems have millions of devices and failure rates are additive

Heterogeneous Memory Architecture



- <u>H</u>eterogeneous <u>Memory Architectures</u> (HMA) consist of multiple memory modules.
 - For example: An HMA system with HBM + DDRx
- Most research on HMAs present only performance trade-offs of placing data in one memory over the other
- Heterogeneity in two axes: 1) Reliability and 2) Performance
- We present techniques to balance both axes

Outline

- Motivation
- Background
- Estimating Data Vulnerability using AVF
- Data AVF vs. Hotness
- Evaluation Methodology
- Results
- Summary

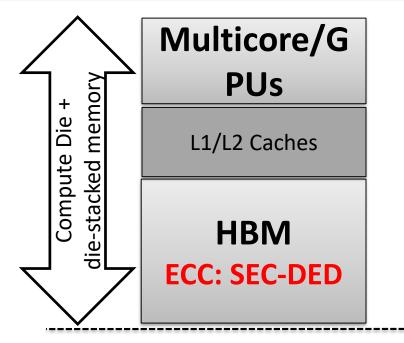
Background: Faults vs. Errors

- Faults are underlying cause of a hardware failure
 - <u>Permanent Faults</u> For example: consistently wrong value returned from memory due to hardware fault (stuck-at bit)
 - <u>Transient Faults</u> For example: soft errors due to singleevent upsets or voltage droop
- Errors are manifestation of faults
 - Errors can be detected and/or corrected. For example using error correcting codes (ECC)

FIT (Failure in Time)

- Failure In Time (FIT) is a measure to quantify system reliability
- 1 FIT for large-scale system such as "Cielo"
 - 1 FIT per node with 8,944 nodes = Failure every 12.8 years
 - 1 FIT per DIMM for 71,552 DIMMs = Failure every **1.6 years**
 - 1 FIT per DRAM 1,144,832 DRAM chips: Failure every **36 days**
- Real FIT rates (FIT rates for components on Cielo)
 - Target socket FIT rate of 1000: failure every 2.3 days
 - Target DRAM chip FIT rate of 35: failure every 1 days

Heterogeneous Memory Architecture (HMA an Example System)



HMA system shows heterogeneity in not only performance but also **reliability**

SEC-DED (ECC)

- <u>Single-bit Error Correct Double-bit Error Detect</u>
- Easy to implement
- Loses efficacy with aging [1]
- 4x-8x higher bandwidth than DDR3

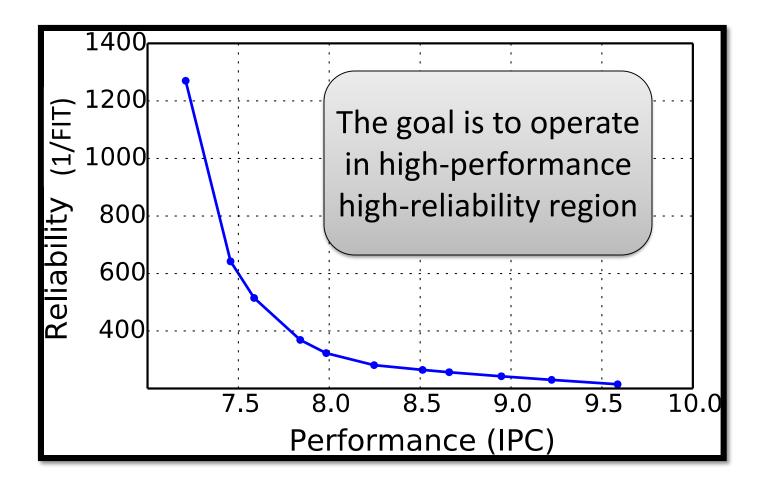


ChipKill (ECC)

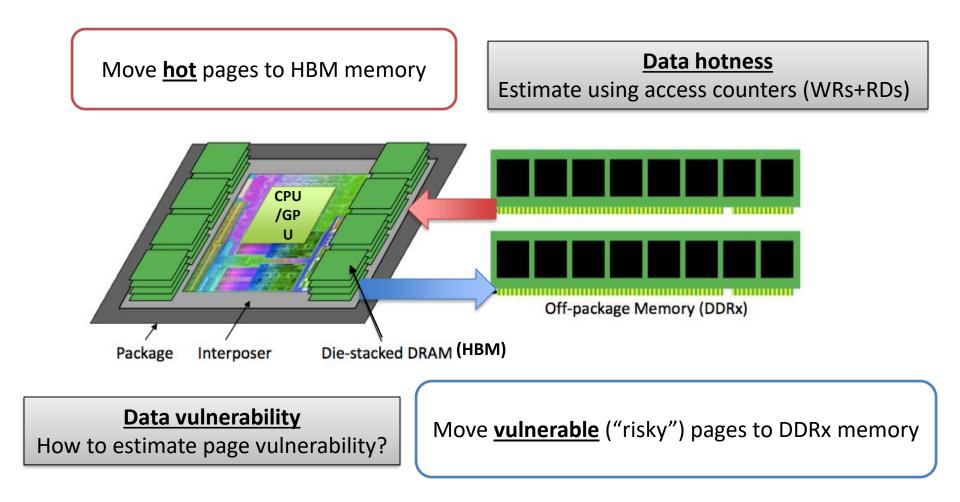
- Symbol-based correcting code
- Requires distributing data to multiple devices
- ChipKill is 42x more effective than SEC-DED [2]
- Low bandwidth

[1] M. Gupta et al. Reliability vs. Performance Trade-off Study of Heterogeneous Memory Architectures in MEMESYS16
[2] V. Sridharan et al. A Study of DRAM Failures in the Field in SC12

Reliability vs. Performance



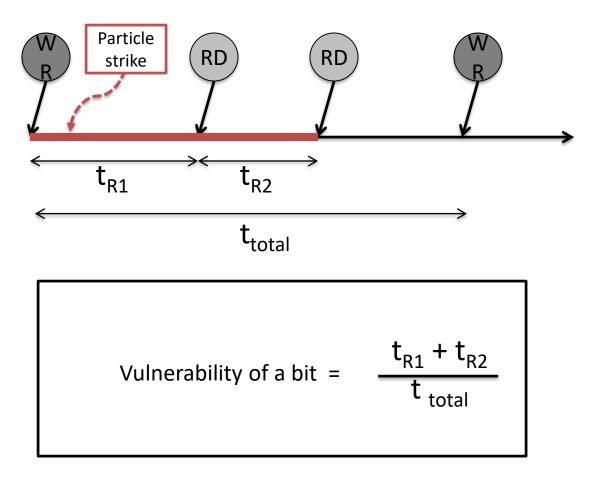
Reliability-aware Data Placement



Outline

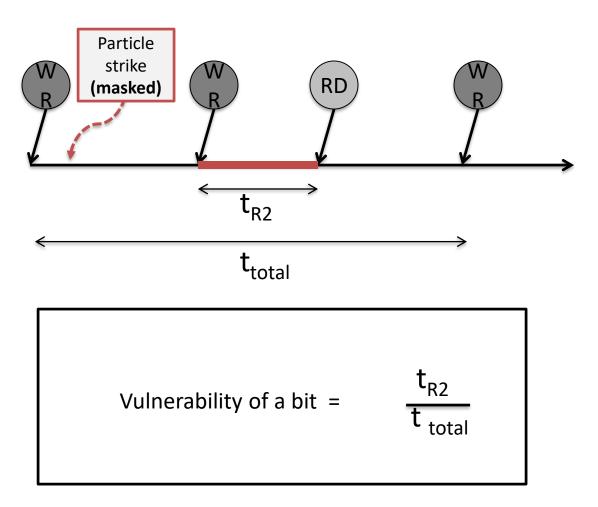
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Data Vulnerability through Architectural Vulnerability Factor (AVF) [1]



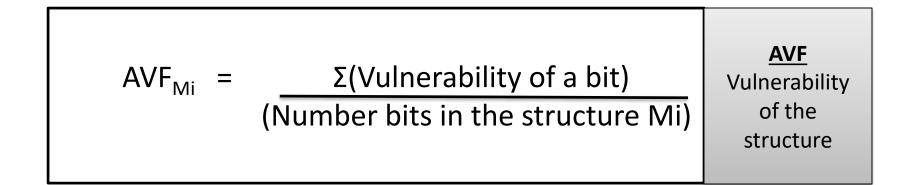
[1] S. Mukherjee et al. A Systematic Methodology to Compute the AVF for a High-Performance Microprocessor in MICRO 2003

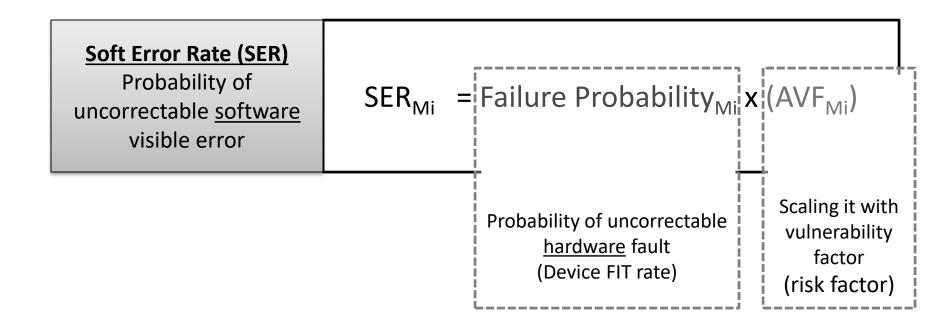
Data Vulnerability through Architectural Vulnerability Factor (AVF) [1]



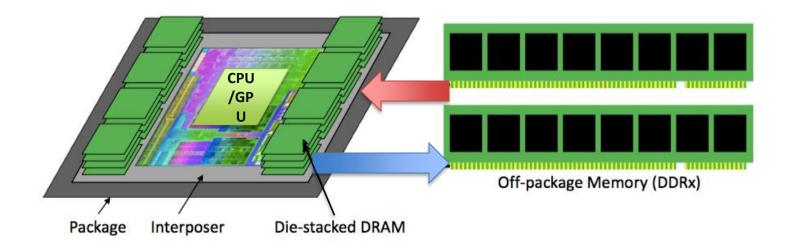
[1] S. Mukherjee et al. A Systematic Methodology to Compute the AVF for a High-Performance Microprocessor in MICRO 2003

Definitions: AVF and SER





The Goal



<u>Memory 1 (HBM)</u>	<u>Memory 2 (DDRx)</u>	
High Bandwidth	Low Bandwidth	
Low Reliability	High Reliability	
Hot & low-risk pages	Cold & high-risk pages	

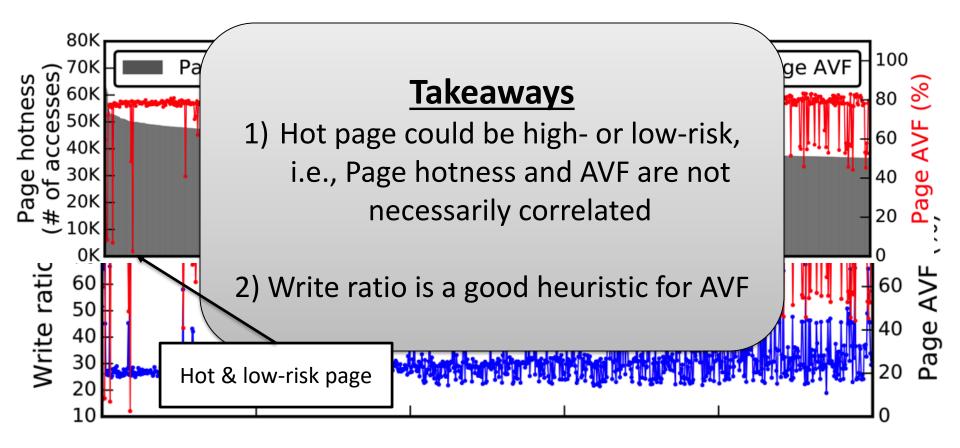
The goal is to find hot & low-risk pages for HBM

Outline

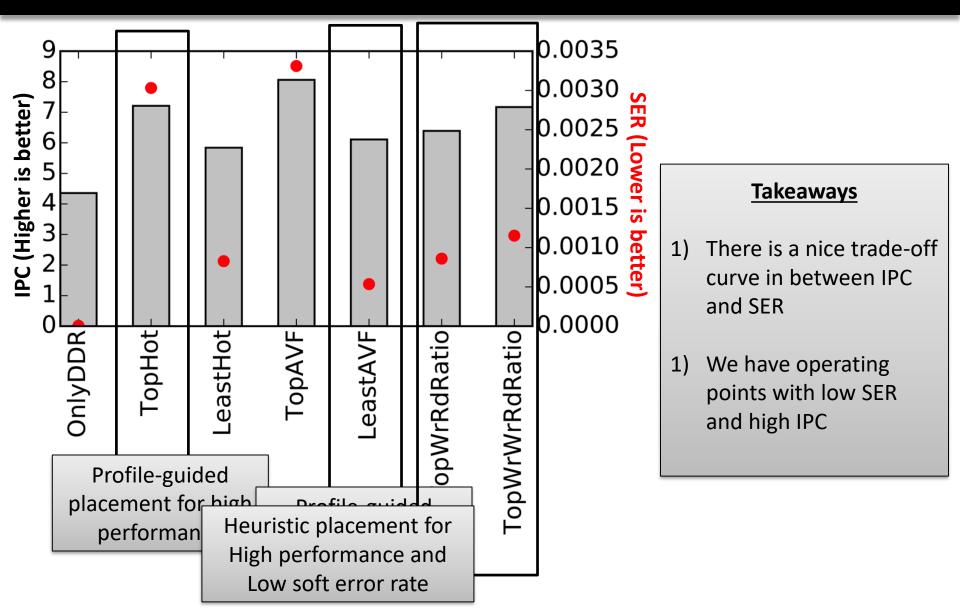
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Data (Memory Page) AVF vs. Hotness

Is hotness correlated with risk (AVF)?



Profile-guided Data Placement (One Workload)



M. Gupta et al. Reliability-aware Data Placement for Heterogeneous Memory Architecture (HPCA18)

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Evaluation Methodology

DRAM Failure Data and Simulation Tools

- Jaguar Cluster [1] with 2.69M DRAM devices
- FaultSim [2] for memory failures and different ECCs
- Ramulator [3] for performance simulations

Evaluation and Results

- On <u>homogeneous</u> and <u>mixed</u> 16-core multi-programmed workloads created using SPEC2006 benchmarks
- We show IPC and SER for different placements averaged for homogenous, mixed, and all workloads

^[1] A Study of DRAM Failures in the Field, Sridharan et al. SC 2012

^[2] FaultSim: <u>https://github.com/Prashant-GTech/FaultSim-A-Memory-Reliability-Simulator</u>, Nair et al. TACO 2016

^[3] Ramulator: https://github.com/CMU-SAFARI/ramulator, Kim et al. IEEE CAL 2015

Outline

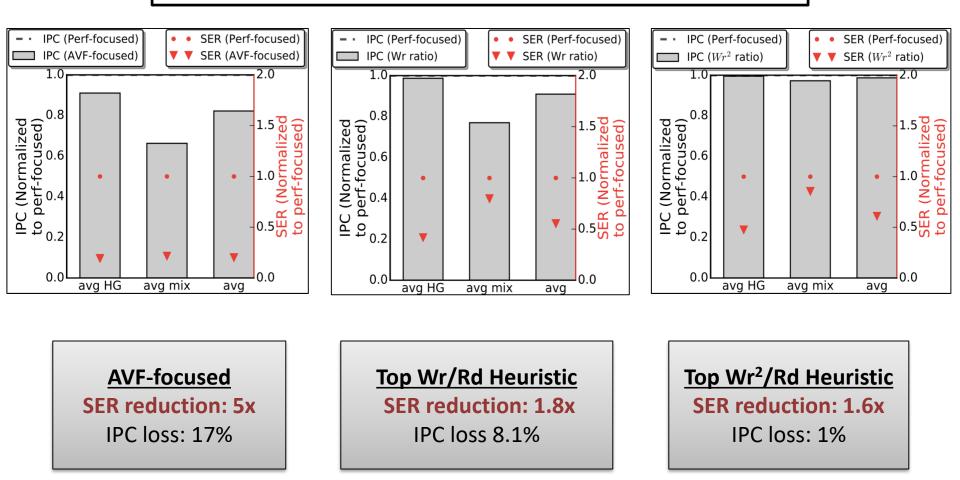
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Profile-guided Data Placement

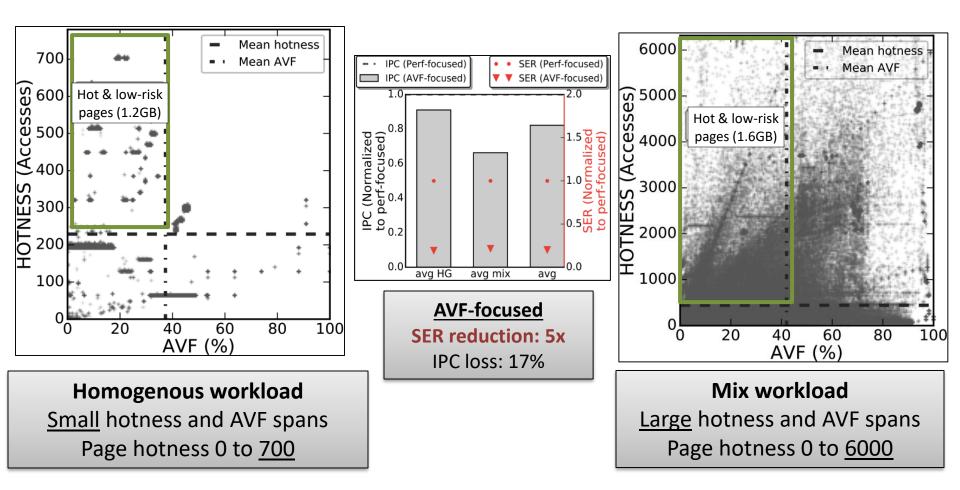
<u>Goal</u>

Reduce **SER** to as low as possible

Keeping IPC as close as possible to performance-focused IPC

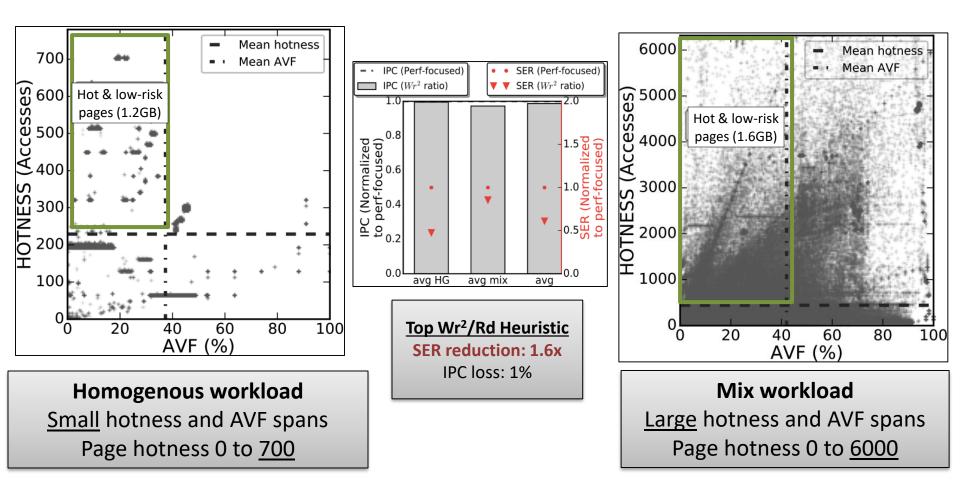


Homogenous vs. Mix Workloads (AVF-focused)



M. Gupta et al. Reliability-aware Data Placement for Heterogeneous Memory Architecture HPCA18

Homogenous vs. Mix Workloads (Wr²/Rd Heuristic)

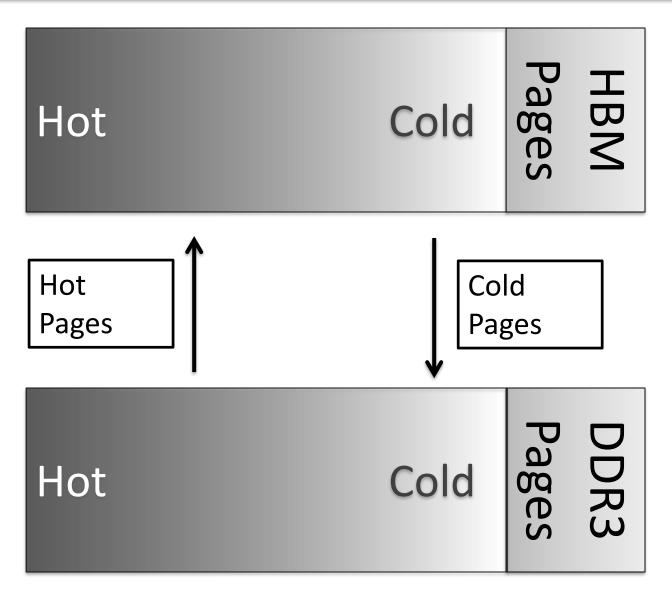


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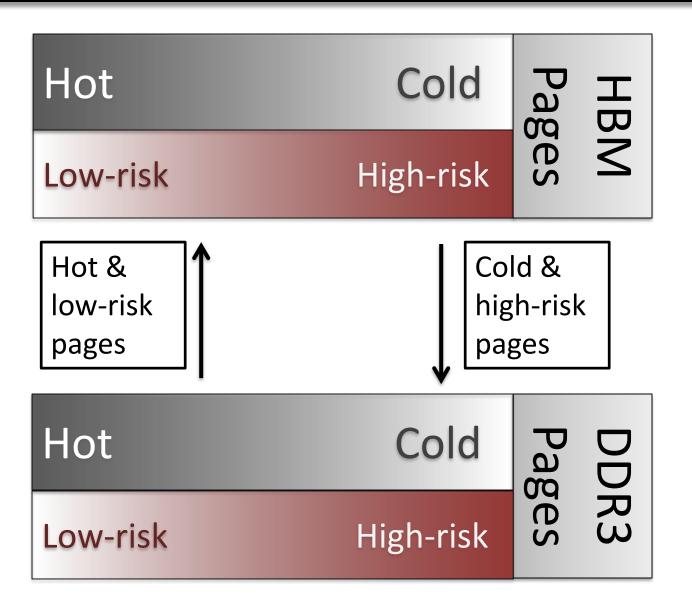
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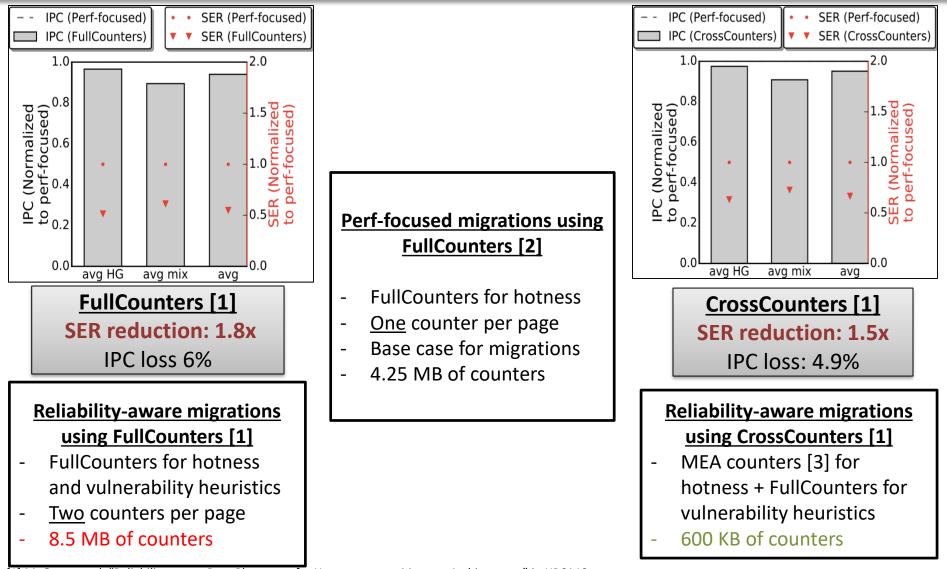
Performance-focused Dynamic Migration



Vulnerability-aware Dynamic Migrations



Reliability-aware Dynamic Migrations [1]



[1] M. Gupta et al. "Reliability-aware Data Placement for Heterogeneous Memory Architectures" in HPCA18

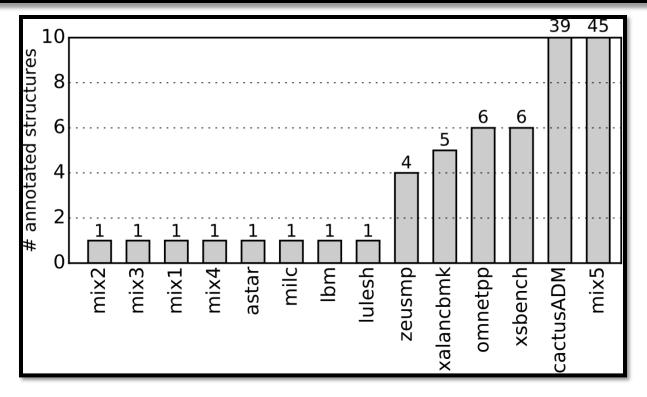
[2] M. Meswani et al. "Heterogeneous Memory Architectures: A HW/SW Approach for Mixing Die-staked and Off-package Memories" in HPCA15

[3] A. Prodromou et al. "MemPod: A Clustered Architecture for Efficient and Scalable Migration in Flat Address Space Multi-level Memories" in HPCA17

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Program Annotations



- Annotating only <u>one</u> program structure pins ~512 MB hot & low-risk data in HBM
- Results in SER reduction of 1.3x at IPC loss of 1.1%
- Thus, minimal program annotation results in improved reliability at marginal performance loss

Summary

Heterogeneous memory architecture are becoming popular

Heterogeneity exists not only in performance, but also in reliability

We discussed techniques to balance both performance and reliability

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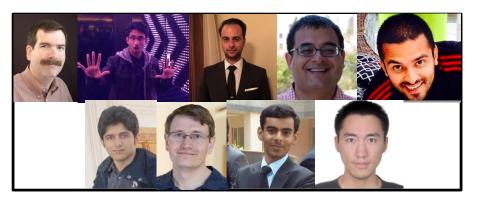
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Backup

Thanks



MESL, UCSD



Architecture Lab, UCSD

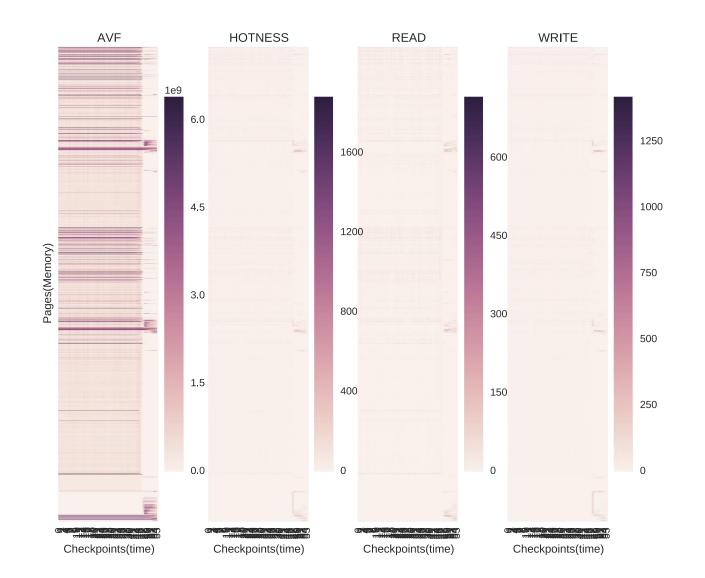


AMD Research

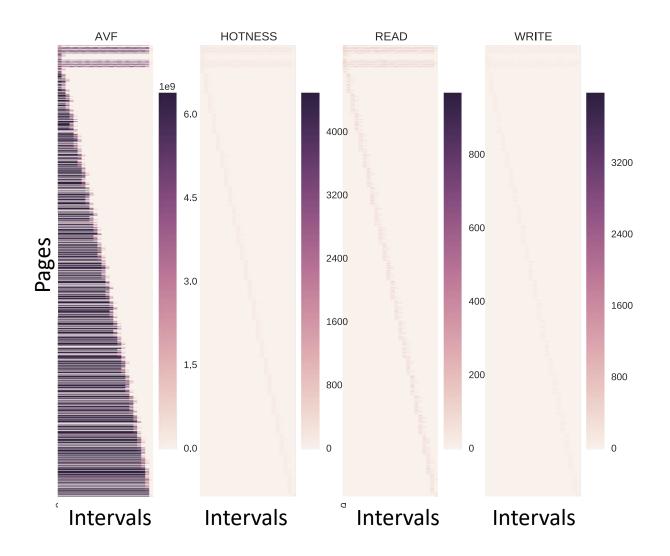


PL, UCSD

Astar Heatmap



Closer Look (Dynamic Migrations)



FaultSim

- Fault Simulation can be using
 - analytical model
 - Interval-based simulations
 - In interval-based simulations, introduces fault in the memory Components based on FIT rates, apply ECC and report error rates
 - Event-based simulations
 - Failure per device happens rarely. Thus, instead of asking random number generate if there's a fault in this interval. One can ask the random number generate what's the timing difference between the next interval.

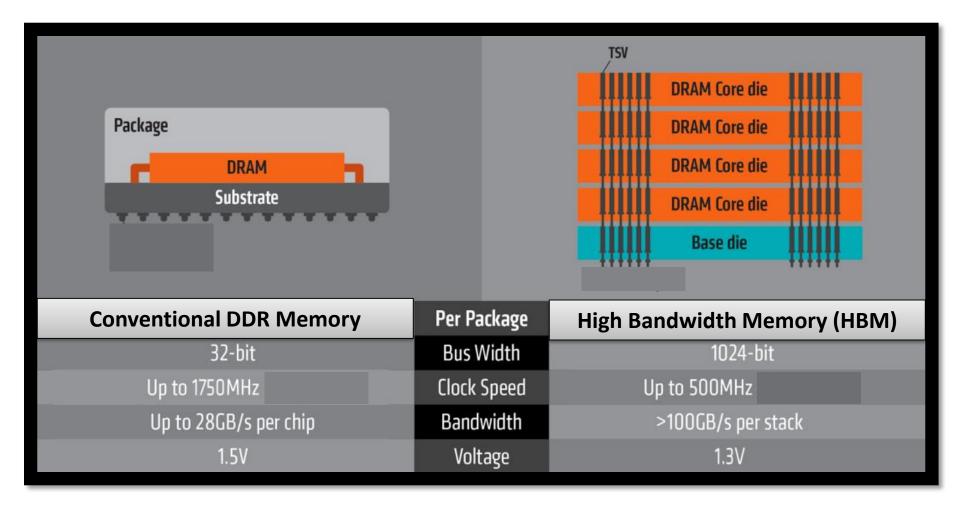
A Study of DRAM Failures in the Field SC 2012

Table I. DRAM Failures per Billion Device Hours (FIT) [Sridharan and Liberty 2012]

	Fault Rate (FIT)	
DRAM Chip Failure Mode	Transient	Permanent
Single bit	14.2	18.6
Single word	1.4	0.3
Single column	1.4	5.6
Single row	0.2	8.2
Single bank	0.8	10
Multibank	0.3	1.4
Multirank	0.9	2.8

- More than 2000 DRAM devices experience a single fault
- Logging using x86 Machine-check registers to log corrected and uncorrected errors
- 250K errors (corrected + uncorrected) per month. 6.6 errors per node per month
- Transient vs. Permanent separation. Using scrubbing interval

High Bandwidth Memory (HBM) [1]



[1] Advanced Microelectronic Devices (AMD Inc.)